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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

J.-S. Mok et al.

Attorney Docket No.: LEPA121687

Application No.: 10/677,182

Art Unit: 1765 / Confirmation No: 8329

Filed:

October 2, 2003

Examiner: S. Ahmed

Title:

METHOD OF FORMING SOLDER RESIST PATTERN

## AMENDMENT AFTER FINAL

Seattle, Washington 98101

January 23, 2007

## TO THE COMMISSIONER FOR PATENTS:

## INTRODUCTORY COMMENTS

Please amend the above-identified application as follows.